

## ABSTRACT OF THE DISCLOSURE

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A design support system includes an information merging section, a connection information generating section and an inter-semiconductor chip and lead frame connection information integrating section. The information merging section captures semiconductor chip information and lead frame information, and generates semiconductor chip and lead frame merged information for each of semiconductor chips. The connection information generating section generates connection information between the semiconductor chips and lead frame from the semiconductor chip and lead frame merged information generated by the information merging section. The inter-semiconductor chip and lead frame connection information integrating section generates integrated connection information between the semiconductor chips and the lead frame, which enables all items of the connection information between the semiconductor chips and lead frame to be displayed on one drawing, from the connection information between the semiconductor chips and lead frame generated by the connection information generating section. The design support system can solve a problem of a conventional design support system in that it is difficult for a user to verify connections between a plurality of semiconductor chips in an MCP (Multi Chip Package).